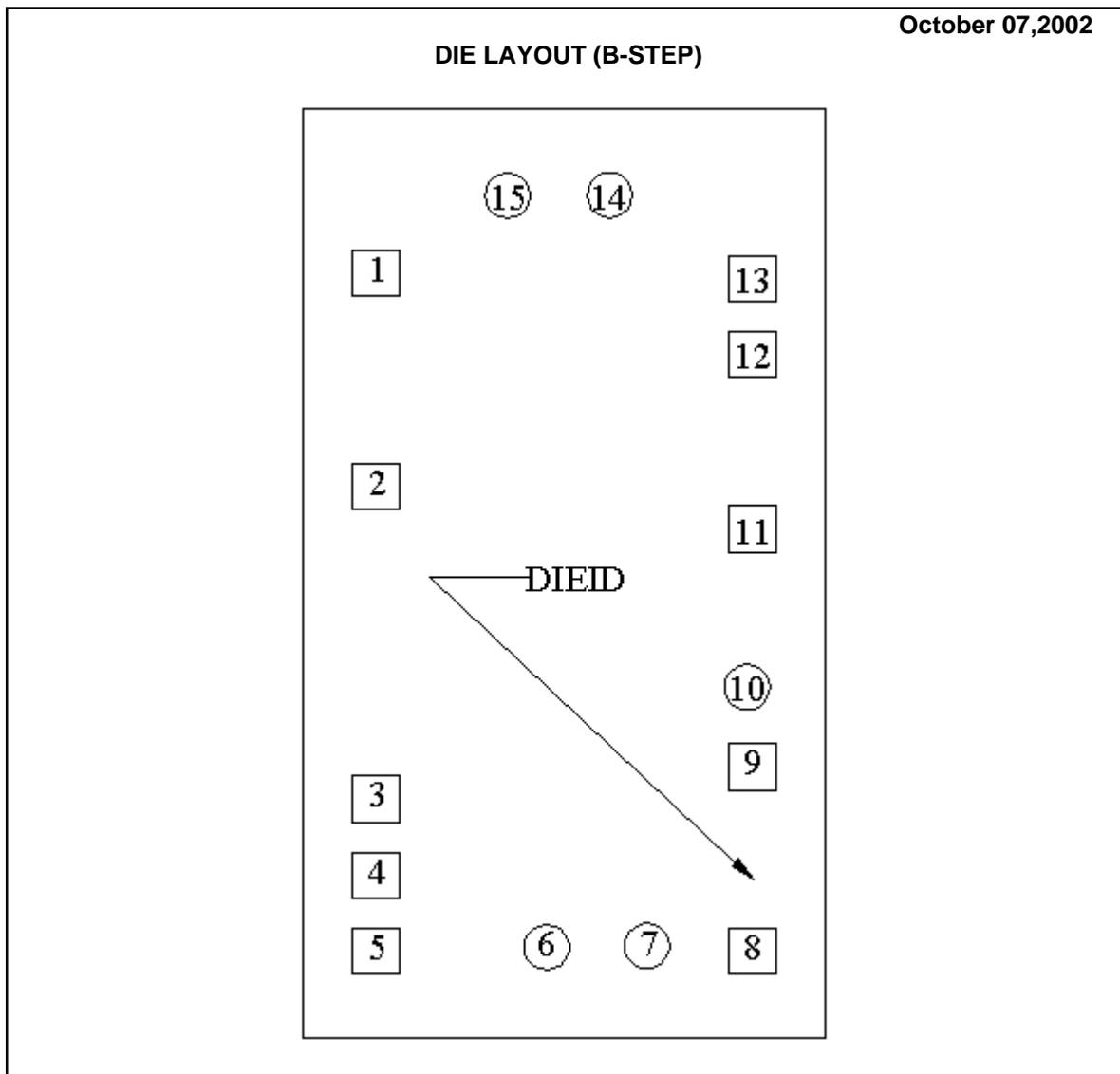


LM2687 MDC MWC
LOW NOISE REGULATED SWITCHED CAPACITOR VOLTAGE INVERTER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM2687B	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	B	Bond Pad Metalization	0.5% COPPER, 1% SILICON, BAL. ALUMINUM, DLM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1041µm x 1854µm 41mils x 73mils	Back Side Connection	Floating
Thickness	216µm Nominal		
Min Pitch	151µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
CAP+	1	-374	599	92	x	92
GND	2	-374	173	92	x	92
GND	3	-374	-449	92	x	92
CAP -	4	-374	-601	92	x	92
/SD	5	-374	-752	92	x	92
NC	6	-36	-744	90	x	90
NC	7	165	-744	90	x	90
VNEG	8	374	-752	92	x	92
VNEG	9	374	-385	92	x	92
NC	10	363	-226	90	x	90
VFB	11	374	88	92	x	92
VOUT	12	374	437	92	x	92
VIN	13	374	588	92	x	92
NC	14	88	753	90	x	90
NC	15	-113	753	90	x	90

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